

IN THE SPECIFICATION

Page 1, above line 1, please insert the following paragraph:

This is a divisional application of U.S. Application No.

09/380,312 filed August 31, 1999. which is a 371 of PCT/JP98/02544 06/08/1998

Please amend the paragraph bridging pages 15 and 16 to read
as follows:

Fig. 1 is a section view showing a resin molded type semiconductor device of an embodiment of the invention, Fig. 1A illustrates the resin contacting the bottom of the chip, Fig. 2 is a plan view showing the resin molded type semiconductor device of the embodiment of the invention, Fig. 3 is an enlarged section view of main portions of the resin molded type semiconductor device of the embodiment of the invention, Fig. 4(a) is a plan view of an inner lead portion of the resin molded type semiconductor device of the embodiment of the invention, Fig. 4(b) is a left side view, Fig. 4(c) is a front view, Fig. 5 is a section view of a resin molded type semiconductor device of the prior art, and Fig. 6 is a section view showing another example of a resin molded type semiconductor device of the prior art.

Page 17, between lines 21 and 22, please insert the following new paragraph: